



CXP88132/88140

CMOS 8-bit Single Chip Microcomputer

Description

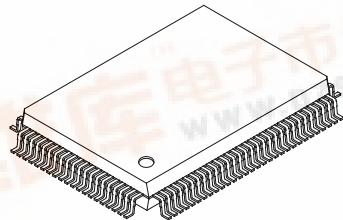
The CXP88132/88140 is a CMOS 8-bit microcomputer which consists of A/D converter, serial interface, timer/counter, time base timer, vector interruption, high precision timing pattern generation circuits, PWM generator, PWM for tuner, VISS/VASS circuit, 32kHz timer/event counter, remote control receiving circuit, FDP controller/driver, VCR vertical sync separation circuit and the measuring circuit which measure signals of capstan FG and drum FG/PG and other servo systems, as well as basic configurations like 8-bit CPU, ROM, RAM and I/O port. They are integrated into a single chip.

Also, CXP88132/88140 provides sleep/ stop function which enables to lower power consumption and ultra-low speed instruction mode in 32kHz operation.

Features

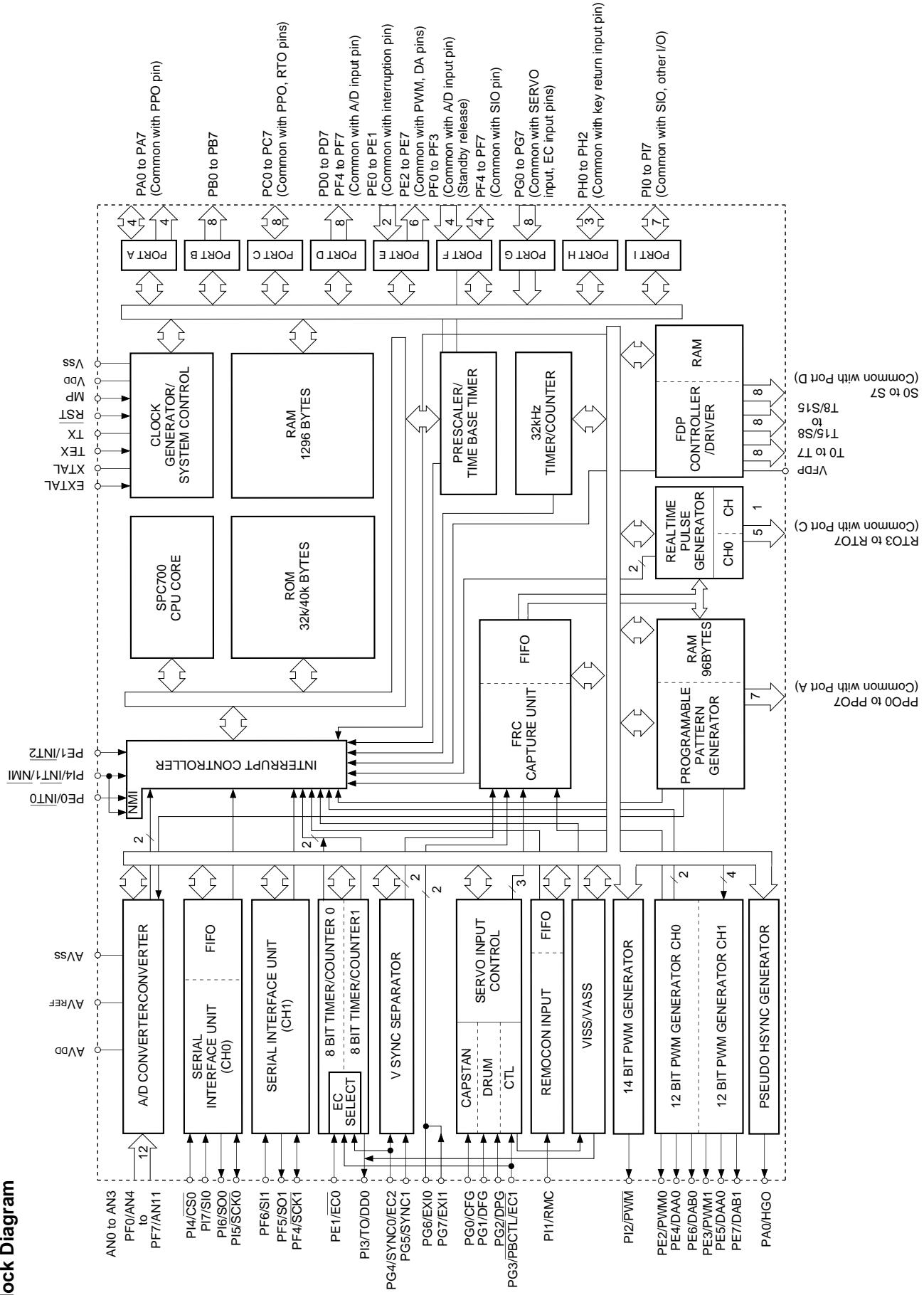
- A wide instruction set (213 instructions) which cover various types of data
 - 16-bit arithmetic instruction/multiplication and division instructions/boolean bit operation instruction
- Minimum instruction cycle During operation 250ns/16MHz, During operation 122μs/32kHz
- Incorporated ROM capacity 32Kbytes (CXP88132), 40Kbytes (CXP88140)
- Incorporated RAM capacity 1296bytes
- Peripheral function
 - A/D converter 8-bit, 8-channel, successive approximation system
(Conversion time: 20.0μs/16MHz)
 - Serial I/O with auto transfer mode Incorporated 8-stage FIFO for data (1 to 8 bytes auto transfer)
 - Timer 8-bit timer/counter, 2-channel, 19-bit time base timer
 - High precision timing pattern generation PPG 8 pins 32-stage programmable circuit RTG 5 pins 2-channel
 - PWM/DA gate output 12-bit, 2-channel (Repetitive frequency 62.5kHz/16MHz)
 - Servo input control Capstan FG, Drum FG/PG, CTL input
 - VSYNC separator
 - FRC capture unit Incorporated 26-bit and 8-stage FIFO
 - PWM output for tuner 14-bit
 - VISS/VASS circuit Pulse duty auto detection circuit
 - 32kHz timer/event counter 32kHz oscillation circuit, ultra-low speed instruction mode
 - Remote control receiving circuit 8-bit pulse measuring counter, 6-stage FIFO
 - FDP controller/driver Max.148 segments can be displayed
 - Tri-state output Hardware key scanning function (Max.16 × 3 key matrix available)
 - Pseudo HSYNC output function PPG 1 pin, RTG 1 pin, output 8 pins
 - High speed head switching circuit
- Interruption 22 factors, 15 vectors, multi-interruption possible
- Standby mode SLEEP/STOP
- Package 100-pin plastic QFP
- Piggyback/evaluation chip CXP88100

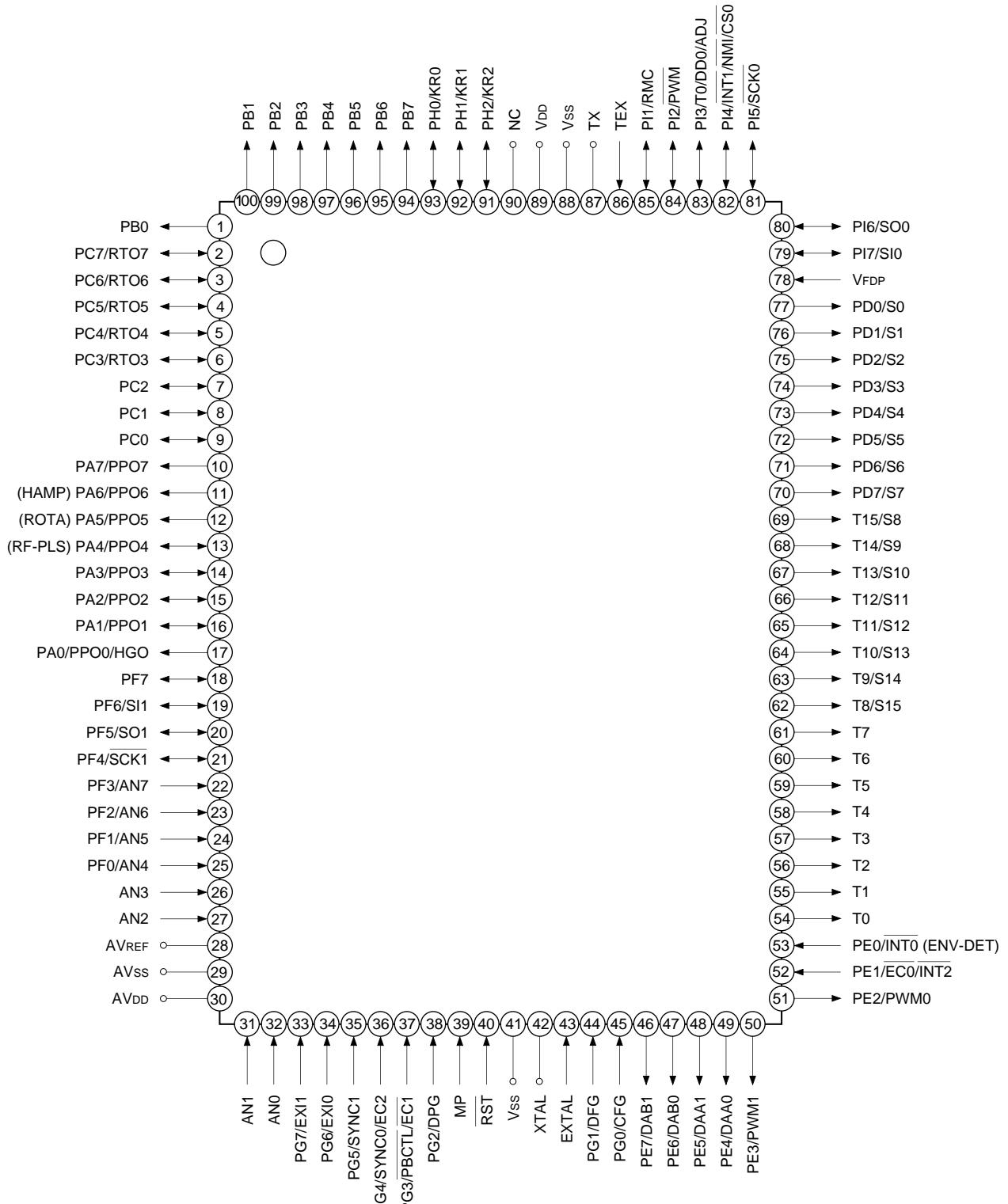
100 pin QFP (Plastic)



Structure

Silicon gate CMOS IC



Pin Configuration (Top View)

Note) 1. NC (Pin 90) is always connected to V_{DD}.
 2. V_{SS} (Pins 41 and 88) are both connected to GND.

Pin Description

Symbol	I/O	Description	
PA0/PPO0/ HGO	Output/Real time output/output	Pseudo HSYNC output pin.	
PA1/PPO1	I/O/ Real time output	(Port A) 8-bit I/O port. Enable to specify I/O by bit unit. Data is gated with RTO content by OR-gate and they are output. (8 pins)	Real-time pulse generator (RTG) output. Functions as high precision real-time pulse output port. (5 pins)
PA2/PPO2			Head switching output pins.
PA3/PPO3			
PA4/PPO4	Output/ Real time output		
PA5/PPO5			
PA6/PPO6			
PA7/PPO7			
PB0 to PB7	Output	8-bit output port. Tri-state can be controlled. (8 pins)	
PC0/PPO8 to PC7/PPO15	Output/ Real time output	(Port C) 8-bit I/O port. Enable to specify I/O by bit unit. Data is gated with RTO content by OR-gate and they are output. (8 pins)	Real-time pulse generator (RTG) output. Functions as high precision real-time pulse output port. (5 pins)
T0 to T7	Output	FDP timing signal output pin.	
T8/S15 to T15/S8	Output/Output	Output pins for FDP timing signal and segment signal.	
PD0 to PD7	Output	(Port D) 8-bit output port. (8 pins)	FDP segment signal output pin.
PE0/INT0	Input/Input	(Port E) 8-bit port. Lower 2 bits are input pins and upper 6 bits are output pins. (8 pins)	Trigger pulse input pin for head switching output. Input pin to request external interruption. Active when falling edge.
PE1/EC0/ INT2	Input/Input/Input		External event input pin for timer/counter. Input pin to request external interruption. Active when falling edge.
PE2/PWM0	Output/Output		PWM output pins. (2 pins)
PE3/PWM1	Output/Output		
PE4/DAA0	Output/Output		
PE5/DAA1	Output/Output		
PE6/DAB0	Output/Output		
PE7/DAB1	Output/Output		DA gate pulse output pins. (2 pins)
AN0 to AN3	Input	Analog input pins to A/D converter. (8 pins)	
PF0/AN0 to PF3/AN3	Input/Input	(Port F) 8-bit I/O port. Enable to specify I/O by bit unit. (8 pins)	
PF4/SCK1	I/O/I/O		Serial clock (CH1) I/O pin.
PF5/SO1	I/O/Output		Serial data (CH1) output pin.
PF6/SI1	I/O/Input		Serial data (CH1) input pin.
PF7	I/O		

Symbol	I/O	Description	
PG0/CFG	Input/Input	(Port G) 8-bit input port. (8 pins)	Capstan FG input pin.
PG1/DFG	Input/Input		Drum FG input pin.
PG2/DPG	Input/Input		Drum PG input pin.
PG3/ <u>PBCTL/EC1</u>	Input/Input/Input		Playback CTL input pin. External event input pin for timer/counter.
PG4/ <u>SYNC0/EC2</u>	Input/Input/Input		Composite sync signal input pin. External event input pin for timer/counter.
PG5/SYNC1	Input/Input		
PG6/EXI0	Input/Input		
PG7/EXI1	Input/Input		External input pin for FRC capture unit.
PH0/KR0 to PH7/KR2	I/O/Input	(Port H) 3-bit I/O port. (3 pins)	Key return input signal for key scanning at FDP segment signal.
PI1/RMC	I/O/Input	(Port I) 8-bit I/O port. Enable to specify I/O by bit unit. (8 pins)	Remote control receiving circuit input pin.
PI2/PWM	I/O/Input		14-bit PWM output pin.
PI3/TO/ DDO/ADJ	I/O/Input		Timer/counter, CTL duty detection, 32kHz oscillation adjustment output pin.
PI4/INT1/ NMI/CS0	I/O/Input/ Input/Input		Input pin to request external interruption, non-maskable interruption and for serial chip select (CH0). Active when falling edge.
PI5/SCK0	I/O/Input		Serial clock (CH1) I/O pin.
PI6/SO0	I/O/Output		Serial data (CH1) output pin.
PI7/SI0	I/O/Input		Serial data (CH1) input pin.
EXTAL	Input		Connecting pin of crystal oscillator for system clock. When supplying the external clock, input the external clock to EXTAL pin and input opposite phase clock to XTAL pin.
XTAL	Output		
TEX	Input	Connecting pin of crystal oscillator for 32kHz timer clock. When used as event counter, input to TEX pin and leave TX pin open. (Feedback resistor is not removed.)	
TX	Output		
RST	Input	System reset pin of active "L" level.	
MP	Input	Microprocessor mode input pin. Always connect to GND.	
V _{FDP}		FPD voltage supply pin when specifying internal resistor by mask option.	
AV _{DD}		Positive power supply pin of A/D converter.	
AV _{REF}	Input	Reference voltage input pin of A/D converter.	
AV _{ss}		GND pin of A/D converter.	
V _{DD}		Positive power supply pin.	
V _{ss}		GND pin. Connect both V _{ss} pins to GND.	

Input/Output Circuit Formats for Pins

Pin	Circuit format	When reset
PA0/PPO0/ HGO 1 pin	<p>Output becomes active from high impedance by data writing to port register.</p>	Hi-Z
PA1/PPO1 1 pin	<p>(Every bit)</p>	Hi-Z
PA2/PPO2 to PA4/PPO4 3 pins	<p>(Every bit)</p>	Hi-Z
PA5/PPO5 to PA7/PPO7 3 pins	<p>Output becomes active from high impedance by data writing to port register.</p>	Hi-Z

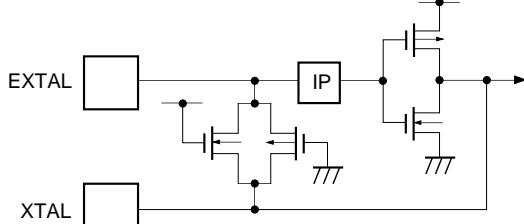
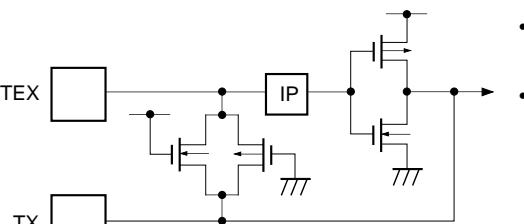
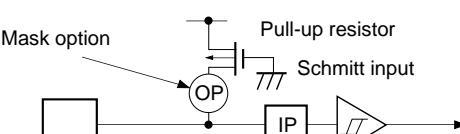
Pin	Circuit format	When reset
PB0 to PB7 8 pins	<p>Port B</p>	Hi-Z
PC0 to PC2 3 pins	<p>Port C</p>	Hi-Z
PC3/RTO3 1 pin	<p>Port C</p>	Hi-Z
PC3/RTO4 1 pin		Hi-Z

Pin	Circuit format	When reset
PC5/RTO5 to PC7/RTO7 3 pins	<p>Port C</p> <p>RTO data</p> <p>Port C data</p> <p>Port C direction</p> <p>(Every bit)</p> <p>IP</p> <p>Input protection circuit</p> <p>Data bus</p> <p>RD (Port C)</p>	Hi-Z
PD0/S0 to PD7/S7 8 pins	<p>Port D</p> <p>Segment output data</p> <p>Output selection control signal ("0" when reset)</p> <p>Port D data</p> <p>High voltage drive transistor</p> <p>OP Mask option</p> <p>Pull-down resistor</p> <p>V_FDP</p> <p>Data bus</p> <p>RD (Port D)</p>	Hi-Z
T0 to T7 8 pins	<p>Timing output data</p> <p>Output selection control signal ("0" when reset)</p> <p>High voltage drive transistor</p> <p>OP Mask option</p> <p>Pull-down resistor</p> <p>V_FDP</p>	Hi-Z
T8/S15 to T15/S8 8 pins	<p>Timing output data</p> <p>Output selection control signal ("0" when reset)</p> <p>Segment output data</p> <p>High voltage drive transistor</p> <p>OP Mask option</p> <p>Pull-down resistor</p> <p>V_FDP</p>	Hi-Z

Pin	Circuit format	When reset
PE0/INT0 PE1/EC0/INT2 2 pins	<p>Port E</p> <p>Schmitt input</p> <p>RD (Port E)</p>	Hi-Z
PE2/PWM0 PE3/PWM1 PE4/DAA0 PE5/DAA1 4 pins	<p>Port E</p> <p>Port E function select</p> <p>DA gate output or PWM output</p> <p>Port E data</p> <p>Data bus</p> <p>RD (Port E)</p> <p>Hi-Z control</p>	Hi-Z
PE6/DAB0 PE7/DAB1 2 pins	<p>Port E</p> <p>Port E function select</p> <p>DA gate output</p> <p>Port E data</p> <p>Data bus</p> <p>RD (Port E)</p> <p>Hi-Z control</p>	High level
PF0/AN4 to PF3/AN7 4 pins	<p>Port F</p> <p>Input multiplexer</p> <p>IP</p> <p>Port F function select</p> <p>To A/D converter</p> <p>Data bus</p> <p>RD (Port F)</p>	Hi-Z
PF4/SCK1 2 pins	<p>Port F</p> <p>SCK1 output enable</p> <p>From serial interface</p> <p>MPX</p> <p>Port F data</p> <p>Port F direction</p> <p>Data bus</p> <p>RD (Port F)</p> <p>To serial interface</p> <p>Schmitt input</p> <p>IP</p>	Hi-Z

Pin	Circuit format	When reset
PF5/SO1 1 pin	<p>Port F</p> <p>Port F output selection</p> <p>From serial interface</p> <p>MPX</p> <p>Port F data</p> <p>Port F direction</p> <p>Data bus</p> <p>RD (Port F)</p> <p>To serial interface</p>	Hi-Z
PF6/SI1 1 pin	<p>Port F</p> <p>Port F data</p> <p>Port F direction</p> <p>Data bus</p> <p>RD (Port F)</p> <p>To serial interface</p> <p>Schmitt input</p>	Hi-Z
PF7 1 pin	<p>Port F</p> <p>Port F data</p> <p>Port F direction</p> <p>Data bus</p> <p>RD (Port F)</p> <p>To serial interface</p>	Hi-Z
PG0/CFG PG1/DFG PG2/DPG PG3/PBCTL/ EC1 PG4/SYNC0/ EC2 PG5/SYNC1 PG6/EXI0 PG7/EXI1 8 pins	<p>Port G</p> <p>Schmitt input</p> <p>IP</p> <p>Data bus</p> <p>RD (Port G)</p> <p>Note) For PG4/SYNC and PG5/SYNC1, CMOS schmitt input or TTL schmitt input can be selected with the mask option.</p>	Hi-Z

Pin	Circuit format	When reset
PI2/PWM PI3/TO/ DDO/ADJ 2 pins	<p>Port I</p>	Hi-Z
PI1/RMC PI4/INT1/ NMI/CS0 PI7/SI0 1 pin	<p>Port I</p>	Hi-Z
PI5/SCK0 PI6/SO0 2 pins	<p>Port I</p>	Hi-Z
PH0/KR0 to PH2/KR2 3 pins	<p>Port H</p>	Hi-Z

Pin	Circuit format	When reset
EXTAL XTAL 2 pins	 <ul style="list-style-type: none"> Shows the circuit composition during oscillation. Feedback resistor is removed during stop. 	Hi-Z
TEX TX 2 pins	 <ul style="list-style-type: none"> Shows the circuit composition during oscillation. Feedback resistor is removed during 32kHz oscillation circuit stop by software. At this time TEX pin outputs "L" level and TX pin outputs "H" level. 	Oscillation
\overline{RST} 1 pin	 <p>Mask option</p> <p>Pull-up resistor</p> <p>Schmitt input</p> <p>OP</p> <p>IP</p> <p>Inverter</p>	Low level
MP 1 pin	 <p>IP</p> <p>Inverter</p> <p>CPU mode</p>	Hi-Z

Absolute Maximum Ratings

(Vss = 0V)

Item	Symbol	Rating	Unit	Remarks
Supply voltage	V _{DD}	−0.3 to +7.0	V	
	AV _{DD}	AV _{ss} to +7.0 ^{*1}	V	
	AV _{ss}	−0.3 to +0.3	V	
Input voltage	V _{IN}	−0.3 to +7.0 ^{*2}	V	
Output voltage	V _{OUT}	−0.3 to +7.0 ^{*3}	V	
Display output voltage	V _{OD}	V _{DD} − 4.0 to V _{DD} + 0.3	V	As P-channel transistor is open drain, V _{DD} is reference.
High level output current	I _{OH}	−5	mA	All pins excluding display outputs (value per pin) ^{*3}
	I _{ODH1}	−15	mA	Display outputs S0 to S7 (value per pin)
	I _{ODH2}	−35	mA	Display outputs T0 to T7, and T8/S15 to T15/S8 (value per pin)
High level total output current	ΣI _{OH}	−50	mA	Total for all pins excluding display outputs
	ΣI _{ODH}	−100	mA	Total for all display outputs
Low level output current	I _{OL}	15	mA	
Low level total output current	ΣI _{OL}	130	mA	Total for all outputs
Operating temperature	T _{opr}	−20 to +75	°C	
Storage temperature	T _{stg}	−55 to +150	°C	
Allowable power dissipation	P _D	600	mW	

^{*1} AV_{DD} and V_{DD} should be set to a same voltage.^{*2} V_{IN} and V_{OUT} should not exceed V_{DD} + 0.3V.^{*3} It specifies output current of general-purpose I/O port.

Note) Usage exceeding absolute maximum ratings may permanently impair the LSI. Normal operation should better take place under the recommended operating conditions. Exceeding those conditions may adversely affect the reliability of the LSI.

Recommended Operating Conditions

(Vss = 0V)

Item	Symbol	Min.	Max.	Unit	Remarks
Supply voltage	V _{DD}	4.5	5.5	V	Guaranteed range during high speed mode (1/2 dividing clock) operation
		3.5	5.5		Guaranteed range during low speed mode (1/16 dividing clock) operation
		2.7	5.5		Guaranteed operation range by TEX clock
		2.5	5.5		Guaranteed data hold operation range during STOP
Analog power supply	A _{V_{DD}}	4.5	5.5	V	*1
High level input voltage	V _{IH}	0.7V _{DD}	V _{DD}	V	*2
	V _{IHS}	0.8V _{DD}	V _{DD}	V	CMOS schmitt input*3
	V _{IHTS}	2.2	V _{DD}	V	TTL schmitt input*4
	V _{IHEX}	V _{DD} – 0.4	V _{DD} + 0.3	V	EXTAL pin*5 TEX pin*6
Low level input voltage	V _{IL}	0	0.3V _{DD}	V	*2
	V _{ILS}	0	0.2V _{DD}	V	CMOS schmitt input*3
	V _{ILTS}	0	0.8	V	TTL schmitt input*4
	V _{ILEX}	-0.3	0.4	V	EXTAL pin*5 TEX pin*6
Operating temperature	To _{pr}	-20	+75	°C	

*1 A_{V_{DD}} and V_{DD} should be set to a same voltage.

*2 Normal input port (each pin of PA1 to PA4, PC, PF0 to PF3, PF5, PF7, PH, PI2, PI3 and PI6), MP pin

*3 Each pin of RST, PE0/INT0, PE1/EC0/INT2, PF4/SCK1, PF6/SI1, PI1/RMC, PI4/CS0/NMI/INT1, PI5/SCK0, PI7/SI1 and PG (For PG4 and PG5, when CMOS schmitt input is selected with mask option)

*4 Each pin of PG4 and PG5 (When TTL schmitt input is selected with mask option)

*5 It specifies only when the external clock is input.

*6 It specifies only when the external event is input.

DC Characteristics

(Ta = -20 to +75°C, Vss = 0V)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
High level output voltage	VOH	PA to PC, PE PF4 to PF7, PH, PI1 to PI7, RST ^{*1} (VOL only)	VDD = 4.5V, IOH = -0.5mA	4.0			V
			VDD = 4.5V, IOH = -1.2mA	3.5			V
Low level output voltage	VOL		VDD = 4.5V, IOL = 1.8mA			0.4	V
			VDD = 4.5V, IOL = 3.6mA			0.6	V
Display output current	IOH	S0 to S7	VDD = 4.5V, VOH = VDD - 2.5V	-8			mA
		S8/T15 to S15/T8, T0 to T7		-20			mA
Open drain output leakage current (P-CH Tr OFF in state)	ILOL	S0 to S7, S8/T15 to S15/T8, T0 to T7	VDD = 5.5V, VOL = VDD - 35V VFDP = VDD - 35V			-20	μA
Pull-down resistor ^{*3}	RL	S0 to S7, S8/T15 to S15/T8, T0 to T7	VDD = 5V, VFDP - VDD = 30V	60	100	270	kΩ
Input current	IIHE	EXTAL	VDD = 5.5V, VIH = 5.5V	0.5		40	μA
			VDD = 5.5V, Vil = 0.4V	-0.5		-40	μA
	IILE	TEX	VDD = 5.5V, VIH = 5.5V	0.1		10	μA
			VDD = 5.5V, Vil = 0.4V	-0.1		-10	μA
	IILR	RST ^{*2}		-1.5		-400	μA
I/O leakage current	IIZ	PA to PC, PE to PI, AN1 to AN3, MP, RST ^{*2}	VDD = 5.5V, VI = 0, 5.5V			±10	μA
Supply current ^{*4}	IDD1	VDD, VSS	16MHz crystal oscillation (C1=C2=15pF), VDD = 5V ± 10% ^{*5}		25	45	mA
	IDDS1		16MHz crystal oscillation (C1=C2=15pF), VDD = 5V ± 10%, SLEEP mode		1.2	8	mA
	IDD2		32kHz crystal oscillation (C1=C2=47pF), VDD = 3V ± 10%		40	100	μA
	IDDS2		32kHz crystal oscillation (C1=C2=47pF), VDD = 3V ± 10%, SLEEP mode		7	30	μA
	IDDS3		VDD = 5.5V, STOP mode (32kHz, 16MHz oscillation stop)			10	μA
Input capacity	CIN	Other than S0 to S15, T0 to T7, PA0, PA5 to PA7 PE2 to PE7 PB, VDD, VSS AVDD, AVSS	Clock 1MHz 0V other than the measured pins		10	20	pF

- *1 RST pin is specified when evaluation mode is in use.
- *2 RST pin specifies the input current when the pull-up resistor is selected, and specifies leakage current when non-resistor is selected.
- *3 When built-in pull-down resistor is selected with mask option.
- *4 When entire output pins are open.
- *5 When setting upper 2 bits (CPU clock selection) of clock control register CLC (address: 0002FEH) to "00" and operating in high speed mode (1/2 dividing clock).

AC Characteristics

(1) Clock timing

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
System clock frequency	fc	XTAL EXTAL	Fig. 1, Fig. 2	1		16	MHz
System clock input pulse width	t _{XL} , t _{XH}	XTAL EXTAL	Fig. 1, Fig. 2 External clock drive	28			ns
System clock input rise and fall times	t _{CR} , t _{CF}	XTAL EXTAL	Fig. 1, Fig. 2 External clock drive			200	ns
Event count clock input pulse width	t _{EH} , t _{EL}	EC0, EC1, EC2	Fig. 3	t _{sys} + 200*			ns
Event count clock input rise and fall times	t _{ER} , t _{EF}	EC0, EC1, EC2	Fig. 3			20	ms
System clock frequency	fc	TEX TX	V _{DD} = 2.7 to 5.5V Fig. 2 (32kHz clock applying condition)		32.768		kHz
Event count clock input pulse width	t _{TL} , t _{TH}	TEX	Fig. 3	10			μs
Event count clock input rise and fall times	t _{TR} , t _{TF}	TEX	Fig. 3			20	ms

* t_{sys} indicates three values according to the contents of the clock control register (address; 00FEH) upper 2 bits (CPU clock selection).

t_{sys} [ns] = 2000/fc (Upper 2 bits = "00"), 4000/fc (Upper 2 bits = "01"), 16000/fc (Upper 2 bits = "11")

Fig. 1. Clock timing

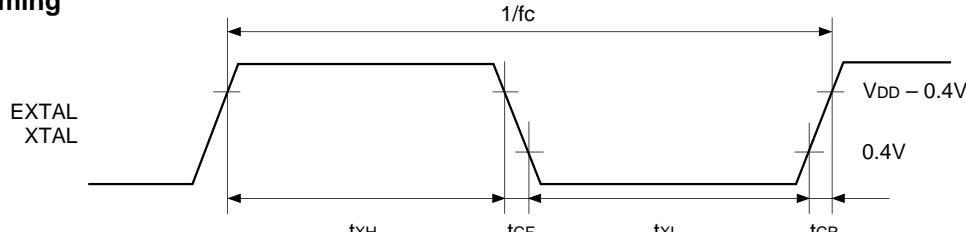


Fig. 2. Clock applying condition

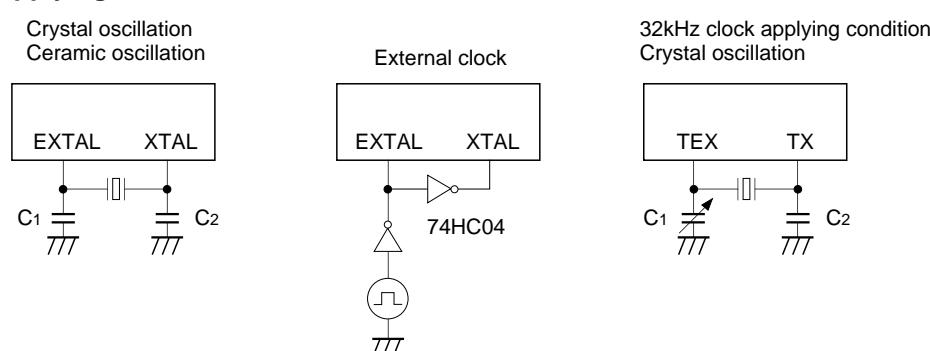
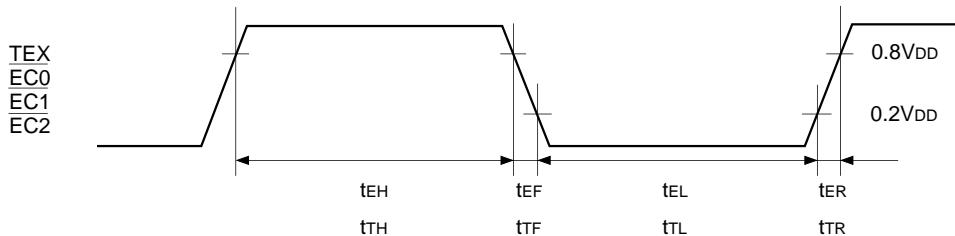


Fig. 3. Event count clock timing**(2) Serial transfer (CH0)**

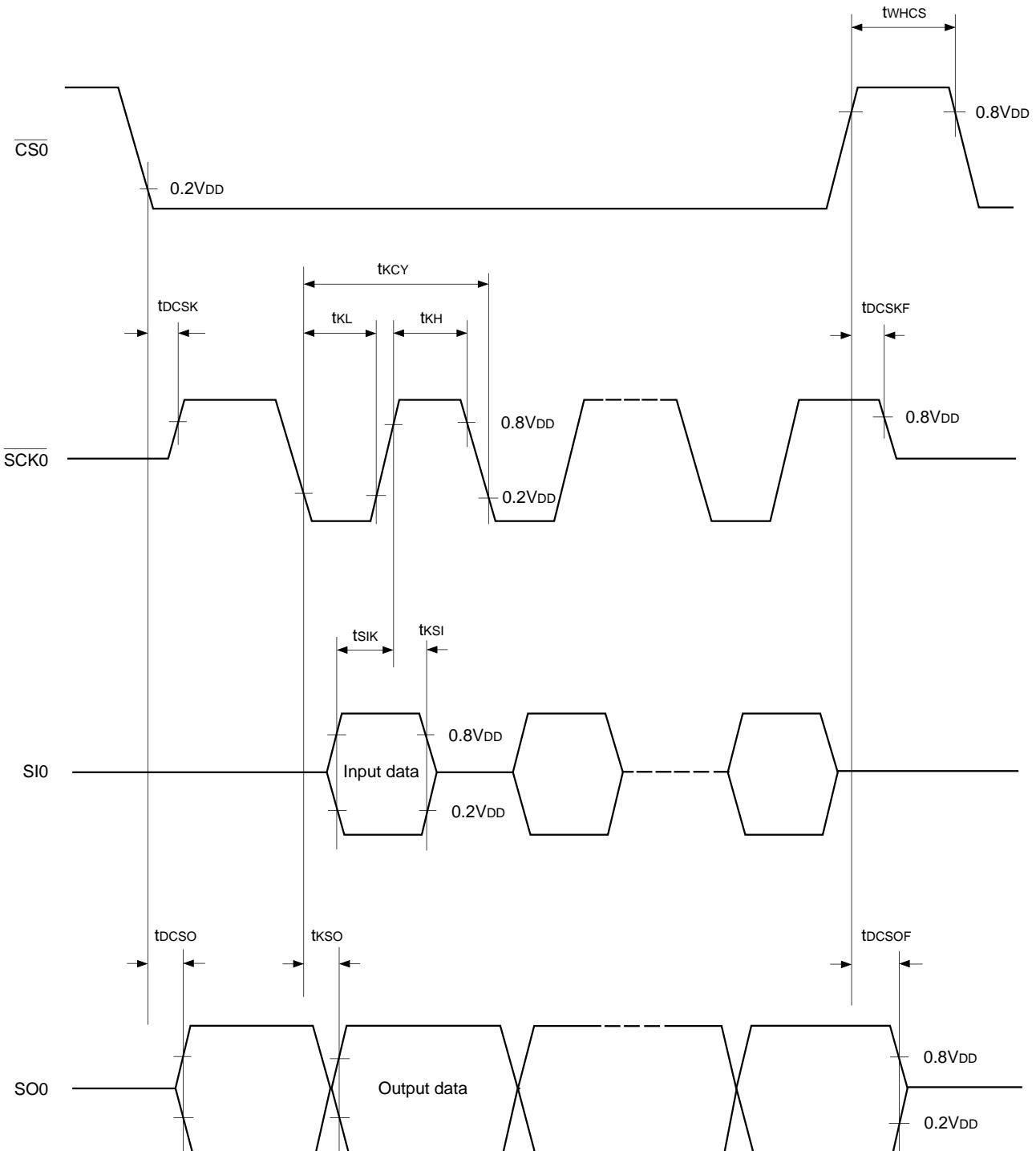
(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
CS0 ↓ → SCK0 delay time	t _{bCSK}	SCK0	Chip select transfer mode (SCK0 = output mode)		t _{sys} + 200	ns
CS0 ↑ → SCK0 floating delay time	t _{bCSKF}	SCK0	Chip select transfer mode (SCK0 = output mode)		t _{sys} + 200	ns
CS0 ↓ → SO0 delay time	t _{bCSO}	SO0	Chip select transfer mode		t _{sys} + 200	ns
CS0 ↑ → SO0 floating delay time	t _{bCSOF}	SO0	Chip select transfer mode		t _{sys} + 200	ns
CS0 high level width	t _{WHCS}	CS0	Chip select transfer mode	t _{sys} + 200		ns
SCK0 cycle time	t _{KCY}	SCK0	Input mode	2t _{sys} + 200		ns
			Output mode	16000/fc		ns
SCK0 high and low level widths	t _{KH} t _{KL}	SCK0	Input mode	t _{sys} + 100		ns
			Output mode	8000/fc - 50		ns
SI0 input set-up time (against SCK0 ↑)	t _{SIK}	SI0	SCK0 input mode	100		ns
			SCK0 output mode	200		ns
SI0 input hold time (against SCK0 ↑)	t _{SKI}	SI0	SCK0 input mode	t _{sys} + 200		ns
			SCK0 output mode	100		ns
SCK0 ↓ → SO0 delay time	t _{kso}	SO0	SCK0 input mode		t _{sys} + 200	ns
			SCK0 output mode		100	ns

Note 1) t_{sys} indicates three values according to the contents of the clock control register (address; 00FEH)
upper 2 bits (CPU clock selection).

t_{sys} [ns] = 2000/fc (Upper 2 bits = "00"), 4000/fc (Upper 2 bits = "01"), 16000/fc (Upper 2 bits = "11")

Note 2) The load of SCK0 output mode and SO0 output delay time is 50pF + 1TTL.

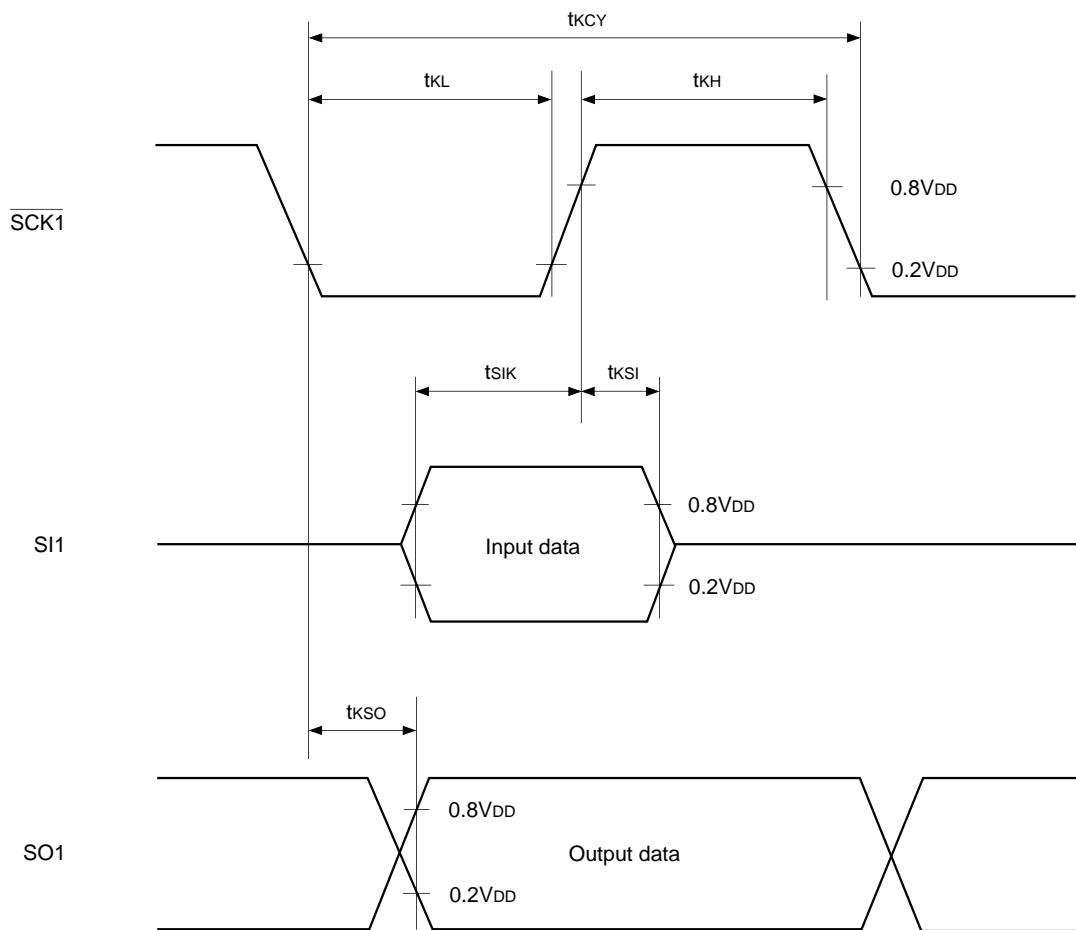
Fig. 4. Serial transfer CH0 timing

Serial transfer (CH1)

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
<u>SCK1</u> cycle time	t _{KCY}	<u>SCK1</u>	Input mode	1000		ns
			Output mode	16000/fc		ns
<u>SCK1</u> high and low level widths	t _{KH} t _{KL}	<u>SCK1</u>	Input mode	400		ns
			Output mode	8000/fc – 50		ns
SI1 input set-up time (against <u>SCK1</u> ↑)	t _{SIK}	SI1	<u>SCK1</u> input mode	100		ns
			<u>SCK1</u> output mode	200		ns
SI1 input hold time (against <u>SCK1</u> ↑)	t _{SKI}	SI1	<u>SCK1</u> input mode	200		ns
			<u>SCK1</u> output mode	100		ns
<u>SCK1</u> ↓ → SO1 delay time	t _{KSO}	SO1	<u>SCK1</u> input mode		200	ns
			<u>SCK1</u> output mode		100	ns

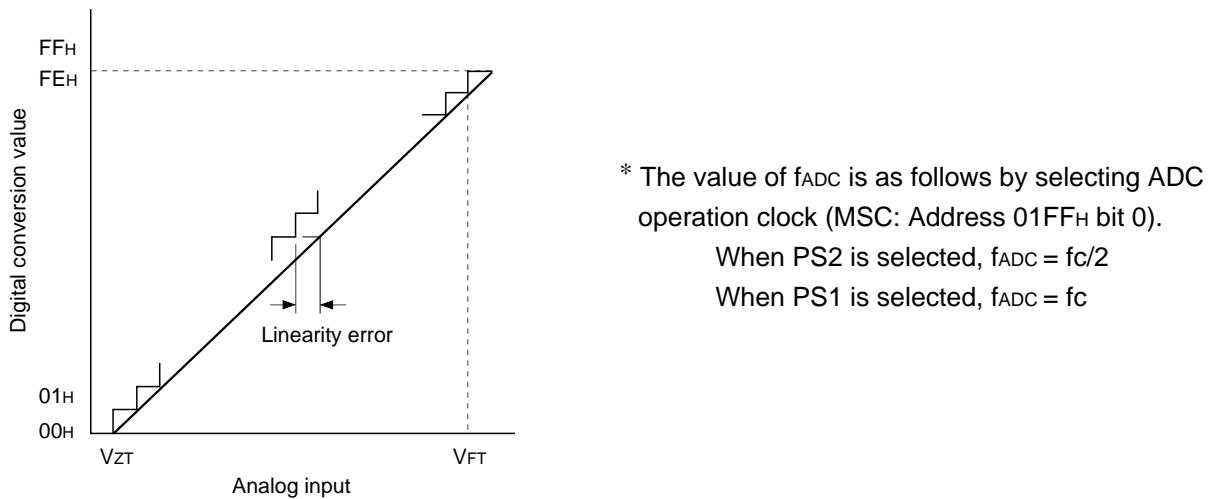
Note) The load of SCK1 output mode and SO1 output delay time is 50pF + 1TTL.

Fig. 5. Serial transfer CH1 timing

(3) A/D converter characteristics (Ta = -20 to +75°C, V_{DD} = AV_{DD} = 4.5 to 5.5V, AV_{REF} = 4.0 to AV_{DD}, V_{SS} = AV_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error			Only for A/D converter operation Ta = 25°C			±1	LSB
Absolute error			V _{DD} = AV _{DD} = AV _{REF} = 5.0V V _{DD} = AV _{SS} = 0V			±2	LSB
Conversion time	t _{CONV}			160/f _{ADC}			μs
Sampling time	t _{SAMP}			12/f _{ADC}			μs
Reference input voltage	V _{REF}	AV _{REF}	V _{DD} = AV _{DD} = 4.5 to 5.5V	AV _{DD} - 0.5		AV _{DD}	V
Analog input voltage	V _{IAN}	AN0 to AN7		0		AV _{REF}	V
AV _{REF} current	I _{REF}	AV _{REF}	Operation mode AV _{REF} = 4.0 to 5.5V		0.6	1.0	mA
			SLEEP mode STOP mode 32kHz operation mode			10	μA

Fig. 6. Definitions of A/D converter terms



(4) Interruption, reset input

(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{ss} = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
External interruption high and low level widths	t _{IH} t _{IL}	INT0 INT1 INT2 NMI		1		μs
Reset input low level width	t _{RSL}	rst		32/fc		μs

Fig. 7. Interruption input timing

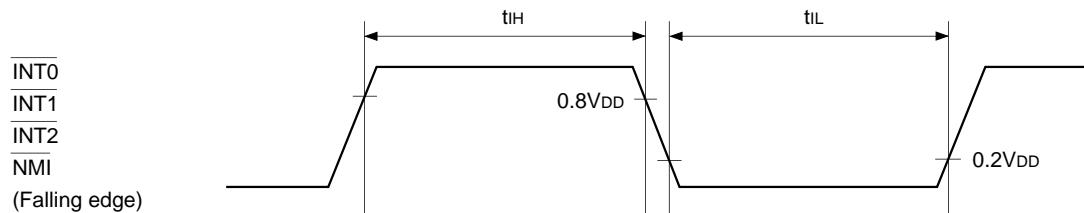
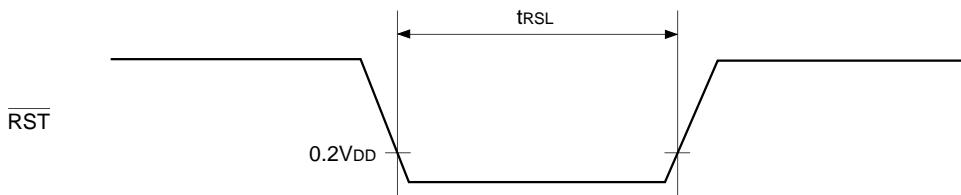


Fig. 8. Reset input timing



(5) Others

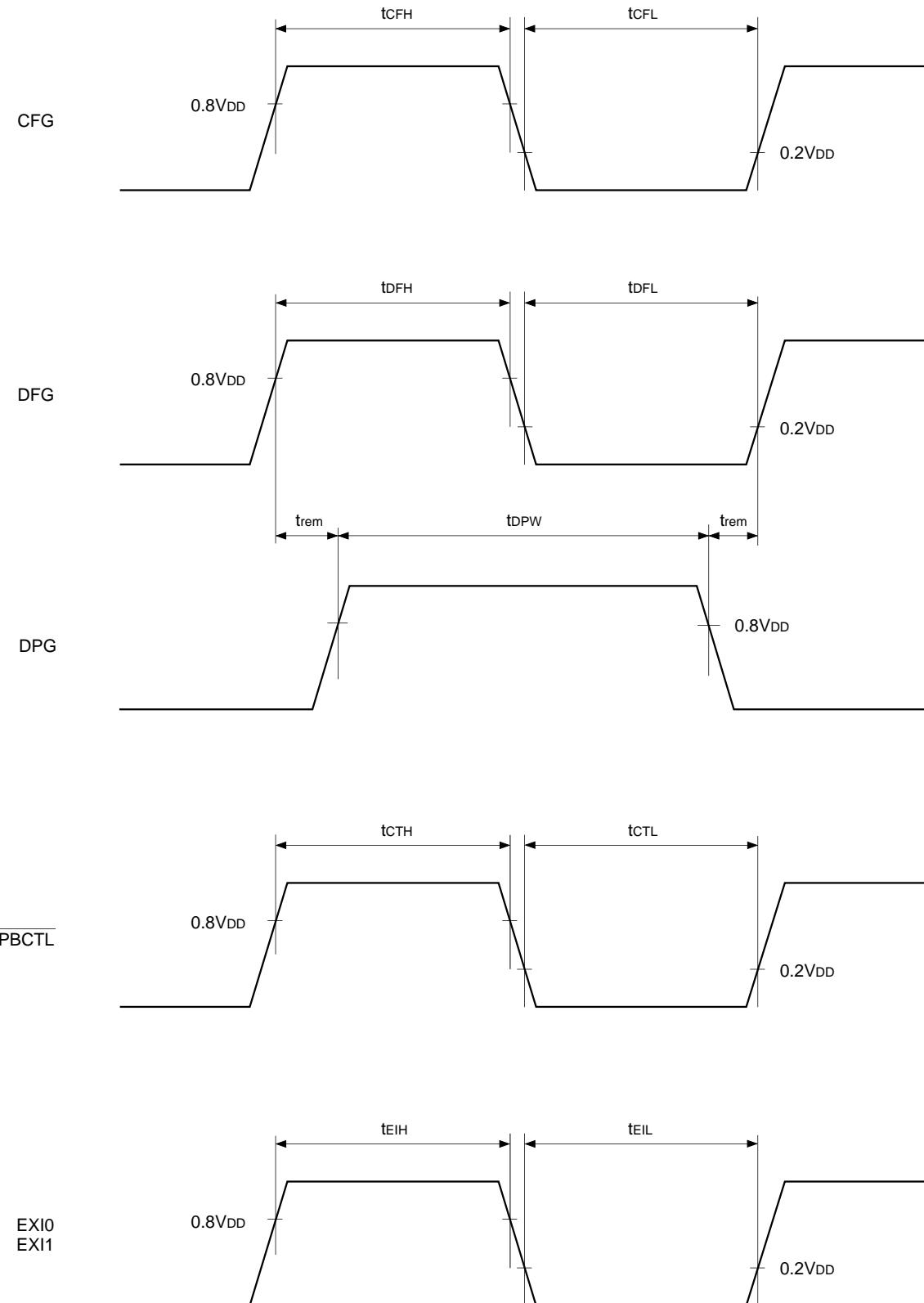
(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{ss} = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
CFG input high and low level widths	t _{CFH} t _{CFL}	CFG		$t_{FRC} \times 24 + 200$		ns
DFG input high and low level widths	t _{DFH} t _{DFL}	DFG		$t_{FRC} \times 16 + 200$		ns
DPG minimum pulse width	t _{DPW}	DPG		$t_{FRC} \times 8 + 200$		ns
DPG minimum removal time	t _{rrem}	DPG		$t_{FRC} \times 16 + 200$		ns
PBCTL input high and low level widths	t _{CTH} t _{CTL}	PBCTL	t _{sys} = 2000/fc	$t_{FRC} \times 8 + t_{sys} + 200$		ns
EXI input high and low level widths	t _{EIH} t _{EIL}	EXI0 EXI1	t _{sys} = 2000/fc	$t_{FRC} \times 8 + t_{sys} + 200$		ns

Note 1) t_{sys} indicates three values according to the contents of the clock control register (address; 00FEH)
upper 2 bits (CPU clock selection).

t_{sys} [ns] = 2000/fc (Upper 2 bits = "00"), 4000/fc (Upper 2 bits = "01"), 16000/fc (Upper 2 bits = "11")

Note 2) t_{FRC} = 1000/fc (ns)

Fig. 9. Other timings

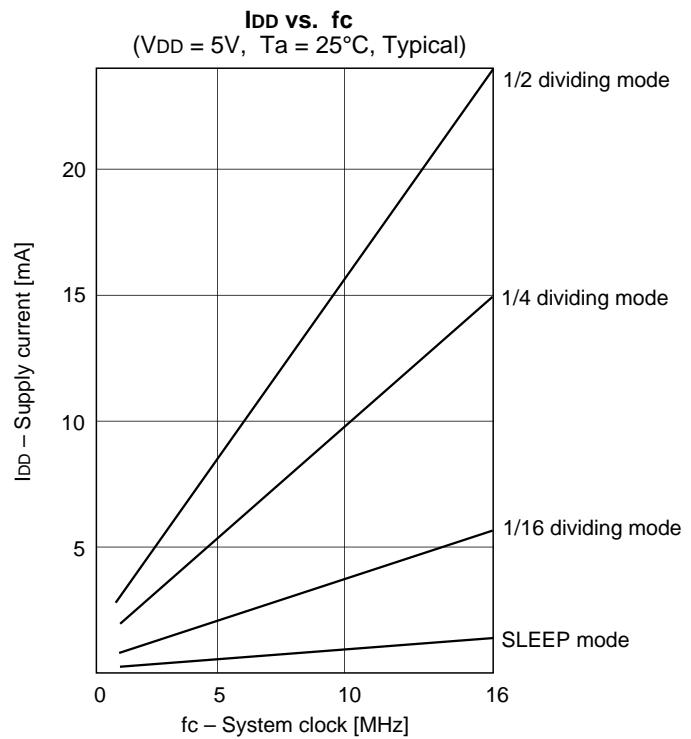
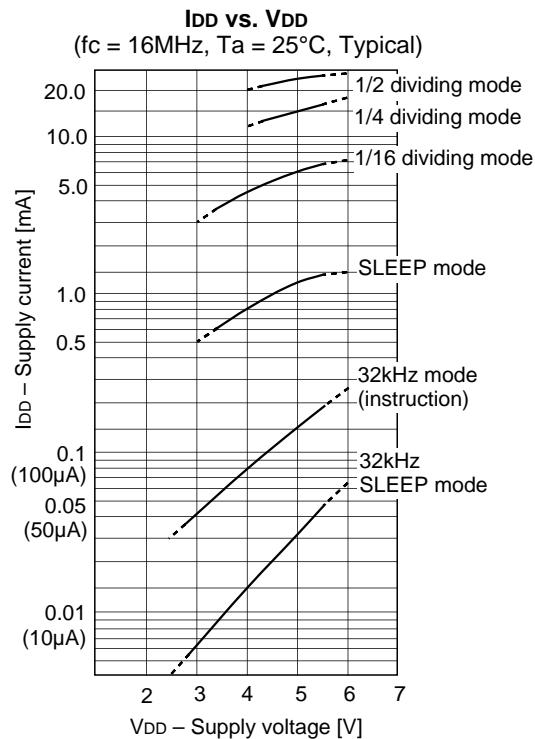
Supplement**Fig. 10. Recommended oscillation circuit**

Manufacturer	Model	fc (MHz)	C ₁ (pF)	C ₂ (pF)	Rd (Ω)	Circuit example		
RIVER ELETEC CO., LTD.	HC-49/U03	8.00	10	10	0	(i)		
		10.00	5	5				
		12.00						
		16.00						
KINSEKI LTD.	HC-49/U (-S)	8.00	22 (15)	22 (15)	0	(i)		
		10.00						
		12.00	15	15				
		16.00	12	12				
	P3	32.768kHz	30	18	470K	(ii)		

Mask option table

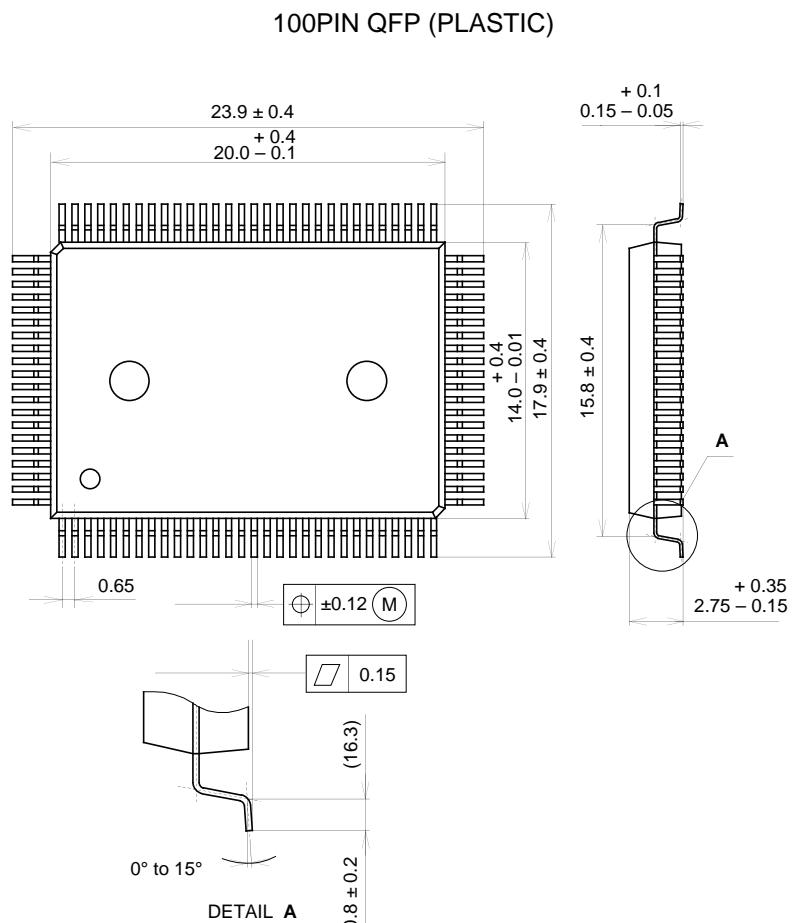
Item	Content	
Reset pin pull-up resistor	Non-existent	Existant
Power-on reset circuit	Non-existent	
High voltage drive output port pull-down resistor	Non-existent	Existant
Input circuit format*	CMOS schmitt	TTL schmitt

* In PG4/SYNC0/EC2 pin and PG5/SYNC1 pin, the input circuit format can be selected every pin.

Characteristics Curve

Package Outline

Unit: mm



PACKAGE STRUCTURE

SONY CODE	QFP-100P-L01
EIAJ CODE	*QFP100-P-1420-A
JEDEC CODE	-----

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER / 42 ALLOY
PACKAGE WEIGHT	1.4g